



Description

WENLAI Power MOSFET is fabricated using **advanced super junction** technology. The resulting device has extremely low on resistance, making it especially suitable for applications which require superior power density and outstanding efficiency.

Features

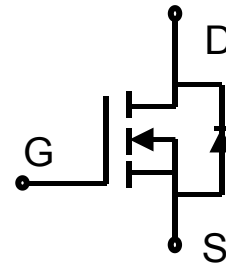
- ◆ Ultra low $R_{DS(on)}$
- ◆ Ultra low gate charge (typ. $Q_g = 21nC$)
- ◆ 100% UIS tested
- ◆ RoHS compliant

Applications

- ◆ Power factor correction (PFC).
- ◆ Switched mode power supplies (SMPS).
- ◆ Uninterruptible power supply (UPS).

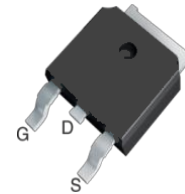
Product Summary

| | |
|----------------------|-------|
| $V_{DS} @ T_{j,max}$ | 700V |
| $R_{DS(on),max}$ | 0.38Ω |
| I_{DM} | 33A |
| $Q_{g,typ}$ | 21nC |



N-Channel MOSFET

Pin Configuration



TO-252

Absolute Maximum Ratings

| Parameter | Symbol | Value | Unit |
|---|----------------|-------------|------------|
| Drain-Source Voltage | V_{DSS} | 650 | V |
| Continuous drain current ($T_C = 25^\circ C$) | I_D | 11 | A |
| | | 7 | A |
| Pulsed drain current ¹⁾ | I_{DM} | 33 | A |
| Gate-Source voltage | V_{GSS} | ± 30 | V |
| Avalanche energy, single pulse ²⁾ | E_{AS} | 270 | mJ |
| Power Dissipation | P_D | 114 | W |
| Operating and Storage Temperature Range | T_J, T_{STG} | -55 to +150 | $^\circ C$ |
| Continuous diode forward current | I_S | 11 | A |
| Diode pulse current | $I_{S,pulse}$ | 33 | A |

Thermal Characteristics

| | | | |
|---|-----------------|-----|--------------|
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 1.1 | $^\circ C/W$ |
| Thermal Resistance, Junction-to-Ambient ³⁾ | $R_{\theta JA}$ | 120 | $^\circ C/W$ |

Package Marking and Ordering Information

| Device | Device Package | Marking | Units/Reel |
|--------------|----------------|--------------|------------|
| WLU380R650GT | TO-252 | WLU380R650GT | 2500 |



Electrical Characteristics T_c = 25°C unless otherwise noted

| Parameter | Symbol | Test Condition | Min. | Typ. | Max. | Unit |
|--------------------------------------|----------------------|--|-------------|--------------|-----------|------|
| Static characteristics | | | | | | |
| Drain-source breakdown voltage | BV _{DSS} | V _{GS} =0 V, I _D =0.25 mA | 650 | - | - | V |
| Gate threshold voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =0.25mA | 2.5 | 3.5 | 4.5 | V |
| Drain cut-off current | I _{DSS} | V _{DS} =650 V, V _{GS} =0 V, T _j = 25°C | - | - | 1 | μA |
| Gate leakage current, Forward | I _{GSSF} | V _{GS} =30 V, V _{DS} =0 V | - | - | 100 | nA |
| Gate leakage current, Reverse | I _{GSSR} | V _{GS} =-30 V, V _{DS} =0 V | - | - | -100 | nA |
| Drain-source on-state resistance | R _{DS(on)} | V _{GS} =10 V, I _D =5.5A T _j = 25°C T _j = 150°C | - - - | 0.34 0.75 | 0.38 - | Ω |
| Gate resistance | R _G | f=1 MHz, open drain | - | 6 | - | Ω |
| Dynamic characteristics | | | | | | |
| Input capacitance | C _{iss} | V _{DS} = 100 V, V _{GS} = 0 V, | - | 920 | - | pF |
| Output capacitance | C _{oss} | f = 250 kHz | - | 35.4 | - | |
| Reverse transfer capacitance | C _{rss} | | - | 0.86 | - | |
| Turn-on delay time | t _{d(on)} | V _{DD} = 400V, I _D = 5.5A | - | 19.6 | - | ns |
| Rise time | t _r | R _G = 10Ω, V _{GS} =10V | - | 36.5 | - | |
| Turn-off delay time | t _{d(off)} | | - | 39 | - | |
| Fall time | t _f | | - | 9.5 | - | |
| Gate charge characteristics | | | | | | |
| Gate to source charge | Q _{gs} | V _{DD} =520 V, I _D =5.5A, | - | 3.6 | - | nC |
| Gate to drain charge | Q _{gd} | V _{GS} =0 to 10 V | - | 6.3 | - | |
| Gate charge total | Q _g | | - | 21 | - | |
| Gate plateau voltage | V _{plateau} | | - | 4 | - | V |
| Reverse diode characteristics | | | | | | |
| Diode forward voltage | V _{SD} | V _{GS} =0 V, I _F =11A | - | - | 1.1 | V |
| Reverse recovery time | t _{rr} | V _R =400 V, I _F =5.5A, | - | 217 | - | ns |
| Reverse recovery charge | Q _{rr} | dI _F /dt=100 A/μs | - | 2.1 | - | μC |
| Peak reverse recovery current | I _{rrm} | | - | 19.6 | - | A |

Notes:

- Limited by maximum junction temperature, maximum duty cycle is 0.75.
- I_{AS} = 3A, L=60mH, V_{DD} = 60V, Starting T_j= 25°C.
- The value of R_{thJA} is measured by placing the device in a still air box which is one cubic foot.



Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

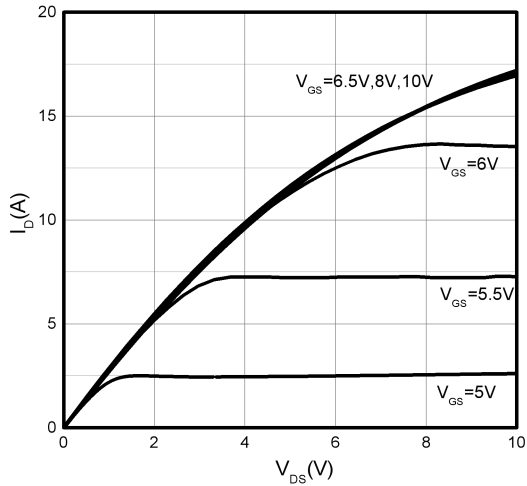


Figure 2. Transfer Characteristics

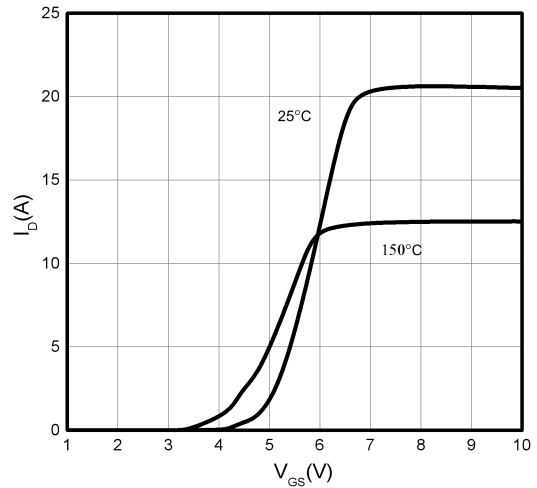


Figure 3. On-Resistance vs. Drain Current

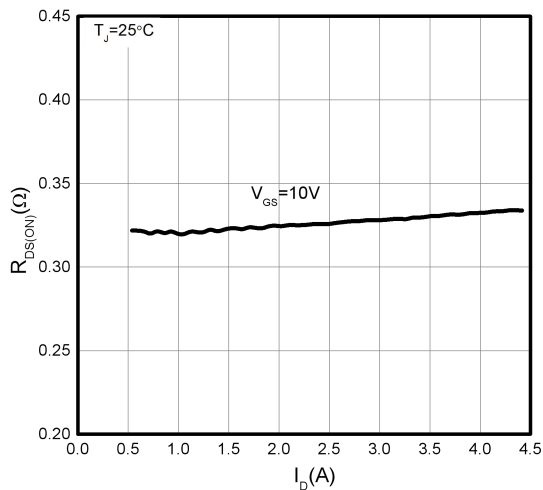


Figure 4. On-Resistance vs. Temperature

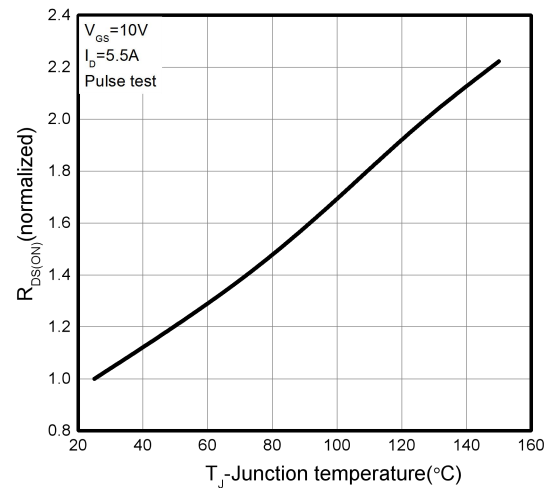


Figure 5. Breakdown Voltage vs. Temperature

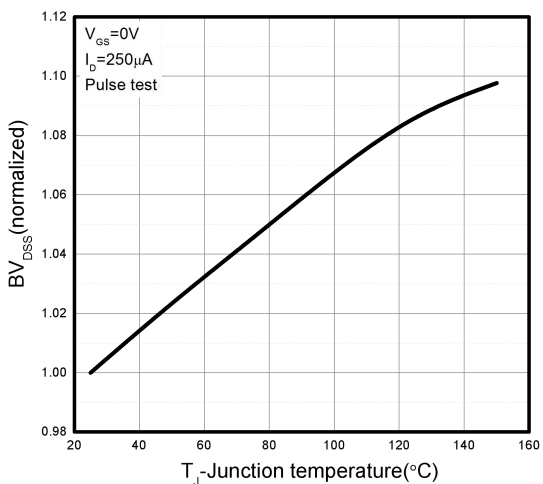


Figure 6. Threshold Voltage vs. Temperature

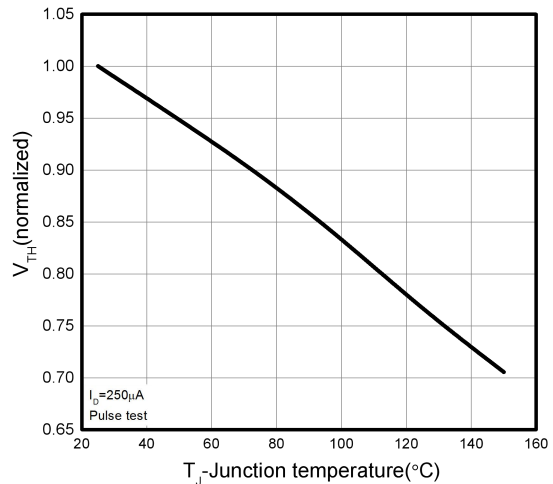




Figure 7. Body-Diode Characteristics

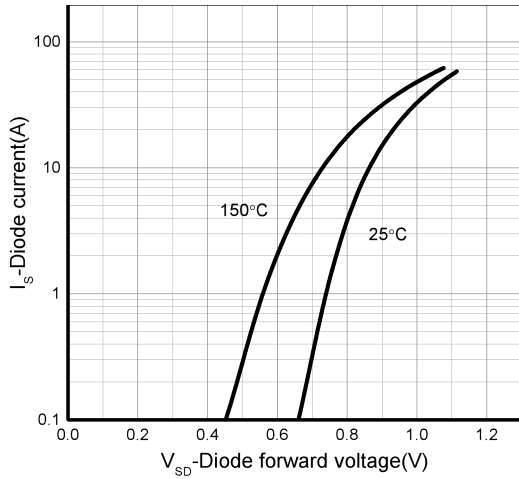


Figure 8. Capacitance Characteristics

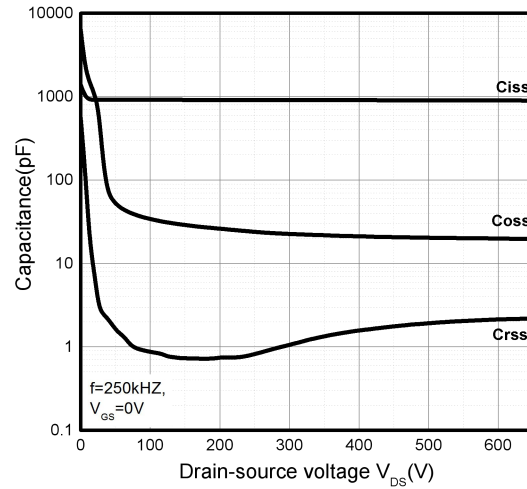


Figure 9. Gate Charge Characteristics

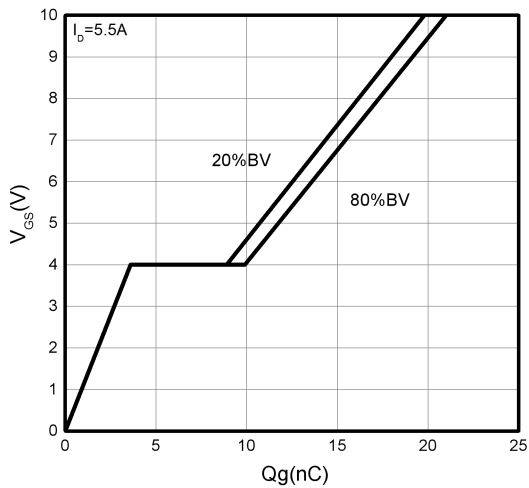


Figure 10. Drain Current Derating

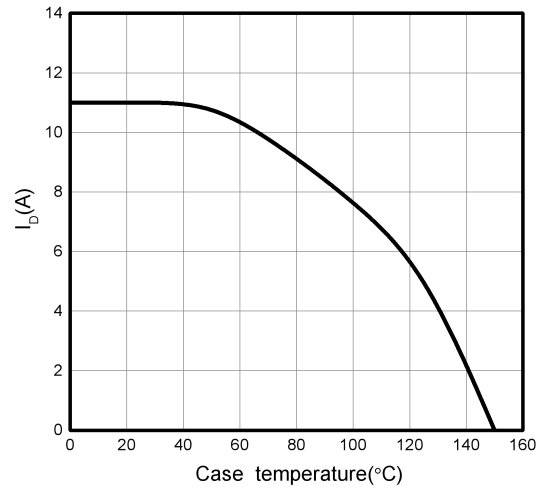


Figure 11. Power Dissipation vs. Temperature

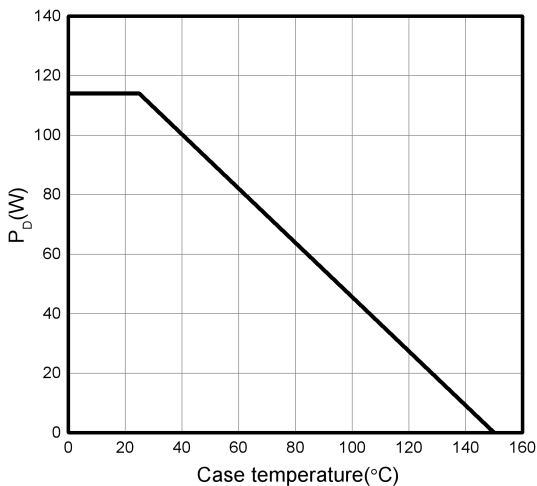


Figure 12. Safe Operating Area

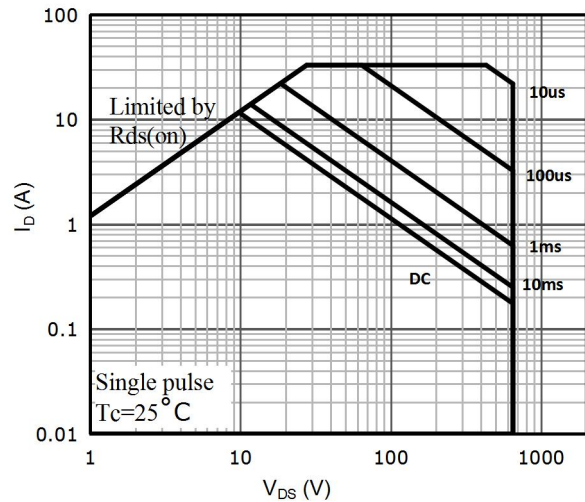
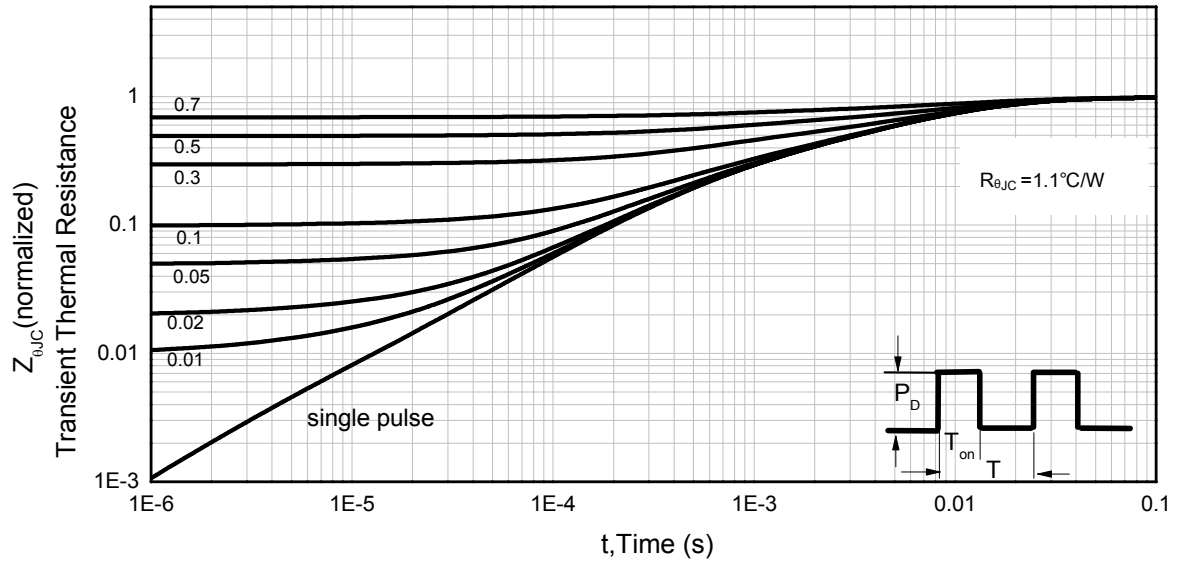




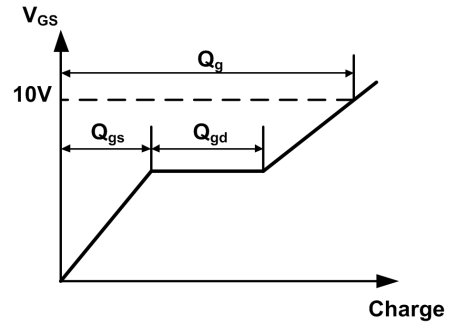
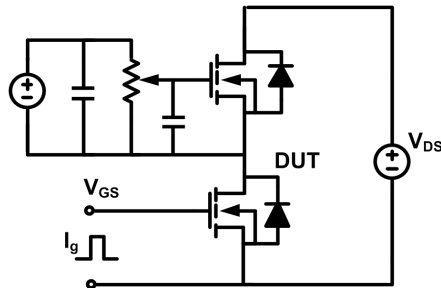
Figure 13. Normalized Maximum Transient Thermal Impedance (RthJC)



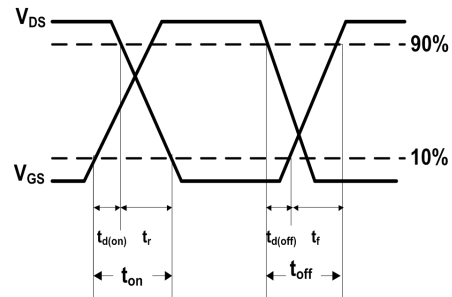
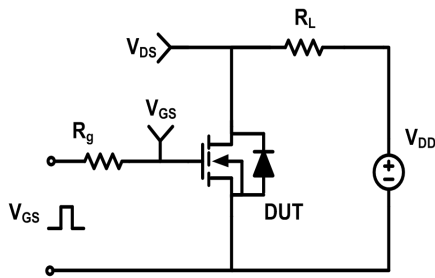


Test Circuit & Waveforms

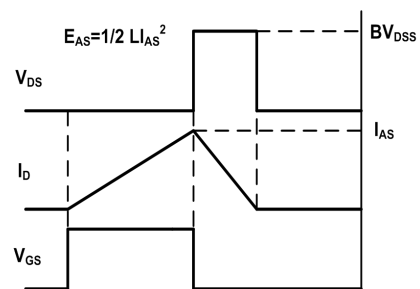
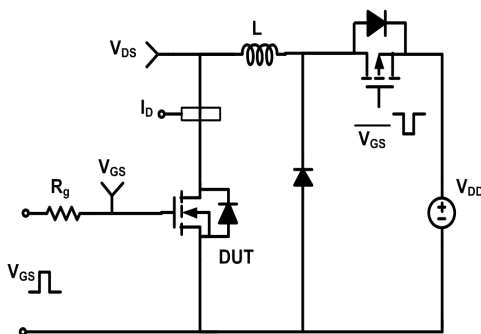
Gate Charge Test Circuit & Waveform



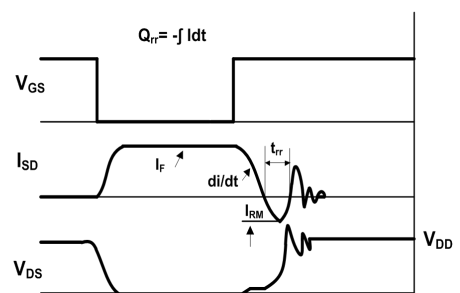
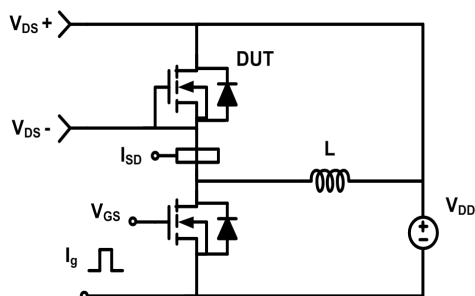
Resistive Switching Test Circuit & Waveform



Unclamped Inductive Switching (UIS) Test Circuit & Waveform

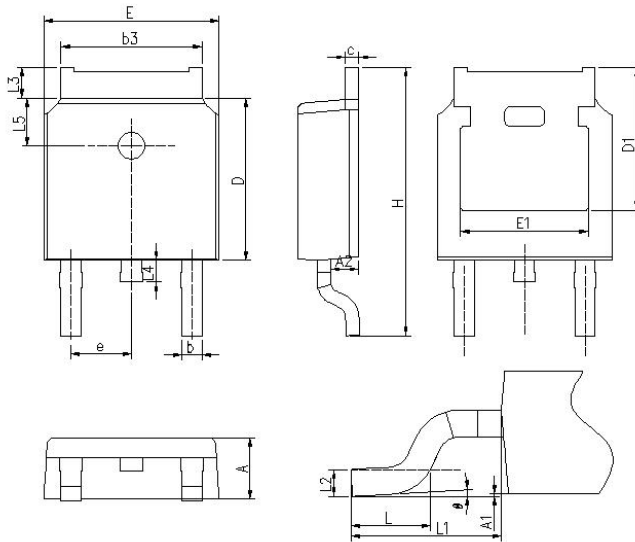


Diode Recovery Test Circuit & Waveform





Mechanical Dimensions for TO-252



| DIMENSIONS IN MILLIMETERS | | |
|---------------------------|----------|------|
| SYMBOL | MIN | MAX |
| A | 2.18 | 2.4 |
| A1 | - | 0.2 |
| A2 | 0.9 | 1.17 |
| b | 0.65 | 0.9 |
| b3 | 4.95 | 5.5 |
| c | 0.43 | 0.89 |
| D | 5.97 | 6.22 |
| D1 | 5.21 | - |
| E | 6.35 | 6.8 |
| E1 | 4.32 | - |
| e | 2.286BSC | |
| H | 9.4 | 10.5 |
| L | 0.38 | 1.78 |
| L1 | 2.90BSC | |
| L2 | 0.51BSC | |
| L3 | 0.88 | 1.28 |
| L4 | - | 1.02 |
| L5 | 1.65 | 1.95 |
| θ | 0° | 10° |



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